

## N-Channel Super Junction Power MOSFET IV

### General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

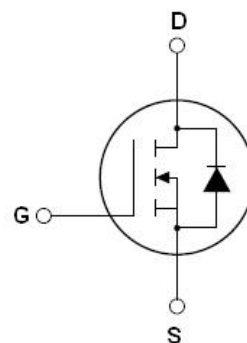
### Features

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

$V_{DS\ min@T_{jmax}}$	650	V
$R_{DS(ON)TYP}$	145	mΩ
$I_D$	21	A
$Q_g$	23	nC

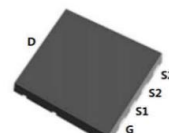


Schematic diagram

✧ Intrinsic fast-recovery body diode

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE60NF160V	DFN8*8	NCE60NF160V



DFN8×8

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	600	V
Gate-Source Voltage ( $V_{DS}=0V$ ) AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	21	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	14.7	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	63	A
Maximum Power Dissipation( $T_c=25^\circ\text{C}$ )	$P_D$	194	W
Derate above $25^\circ\text{C}$		1.29	W/ $^\circ\text{C}$
Single pulse avalanche energy (Note 2)	$E_{AS}$	64	mJ
Avalanche current (Note 1)	$I_{AR}$	4	A
Repetitive Avalanche energy, $t_{AR}$ limited by $T_{jmax}$ (Note 1)	$E_{AR}$	0.35	mJ
Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$ ,	$dv/dt$	50	V/ns
Reverse diode $dv/dt$ , $V_{DS} \leq 480\text{ V}, I_{SD} < I_D$	$dv/dt$	50	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+175	$^\circ\text{C}$

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.77	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	$^{\circ}\text{C}/\text{W}$

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	600			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			200	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	3	4	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10.5A		145	160	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1.0MHz		1200	1400	pF
Output Capacitance	C <sub>oss</sub>			50		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			1.5		pF
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =10.5A, V <sub>GS</sub> =10V		23		nC
Gate-Source Charge	Q <sub>gs</sub>			9		nC
Gate-Drain Charge	Q <sub>gd</sub>			6.5		nC
Gate plateau voltage	V <sub>gp</sub>			6.1		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		2		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =10.5A, R <sub>G</sub> =1.7Ω,V <sub>GS</sub> =10V		42		nS
Turn-on Rise Time	t <sub>r</sub>			18		nS
Turn-Off Delay Time	t <sub>d(off)</sub>			90		nS
Turn-Off Fall Time	t <sub>f</sub>			24		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T <sub>C</sub> =25℃			18	A
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>				54	A
Forward On Voltage	V <sub>SD</sub>	T <sub>j</sub> =25℃,I <sub>SD</sub> =21A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>j</sub> =25℃,I <sub>F</sub> =10.5A, di/dt=100A/μs		113		nS
Reverse Recovery Charge	Q <sub>rr</sub>			0.5		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			8		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.  $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

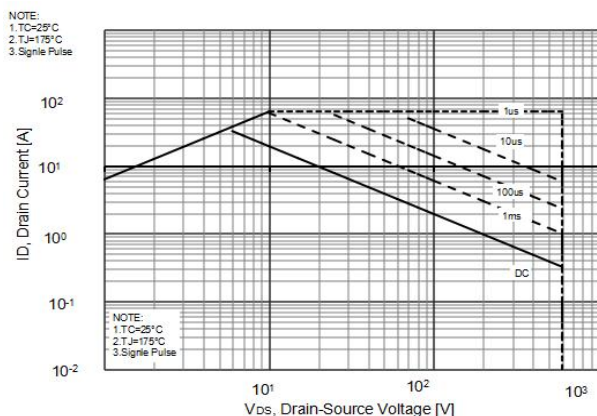


Figure2. Capacitance

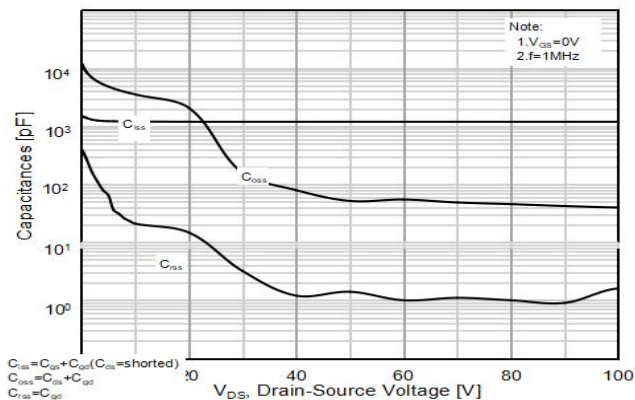


Figure3. Source-Drain Diode Forward Voltage

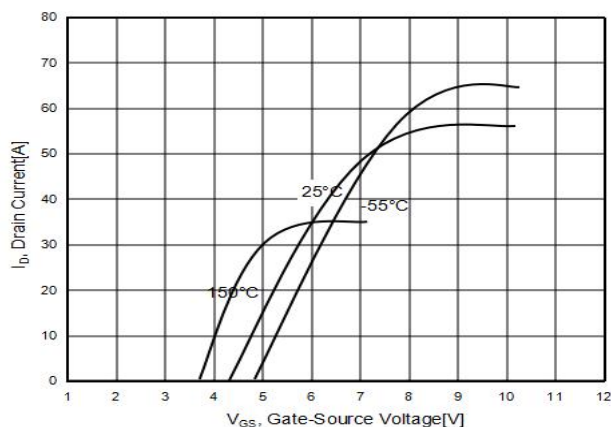


Figure4. Output characteristics

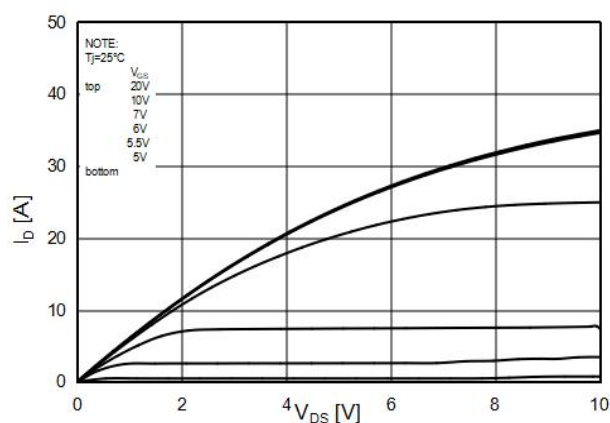


Figure5.  $R_{DS(ON)}$  vs Junction Temperature

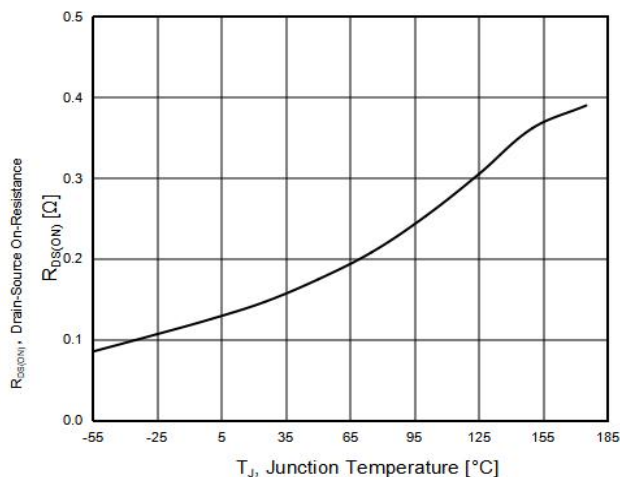


Figure6.  $BV_{DSS}$  vs Junction Temperature

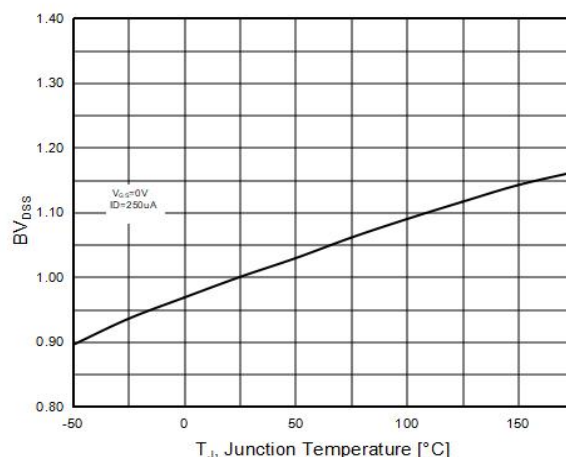


Figure7. Maximum  $I_D$  vs Junction Temperature

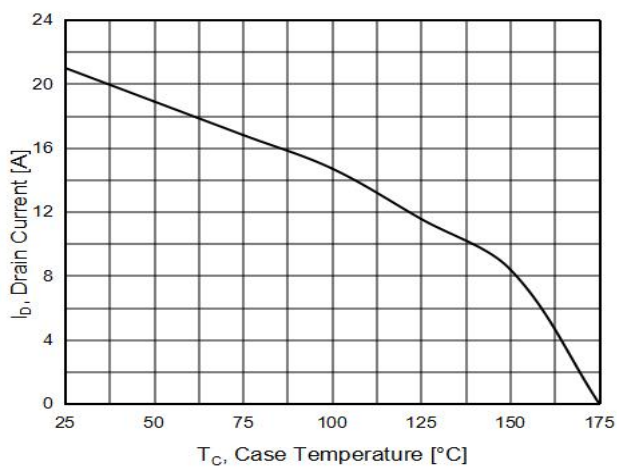


Figure8. Gate charge waveforms

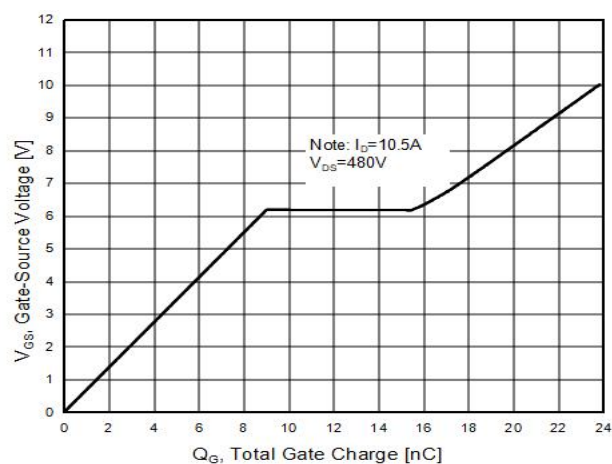


Figure9. Static drain-source on resistance

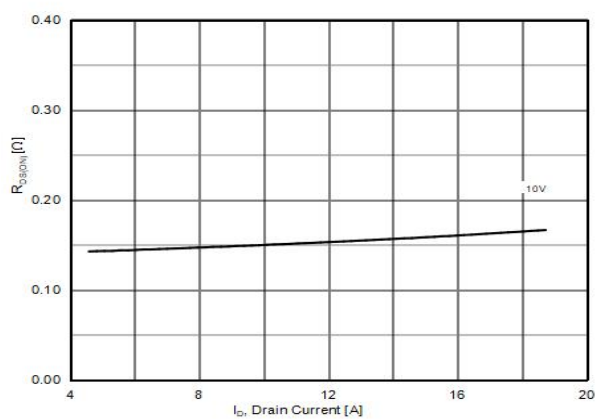
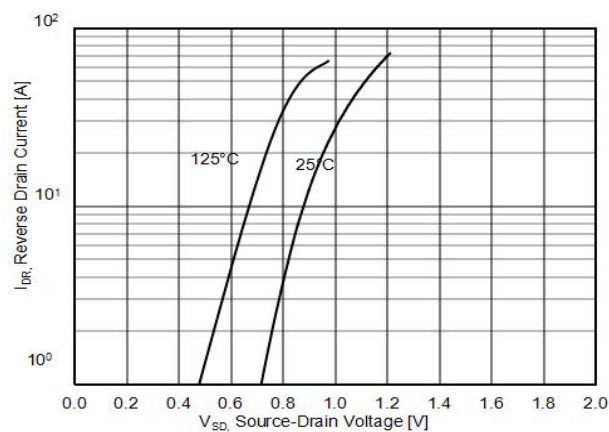
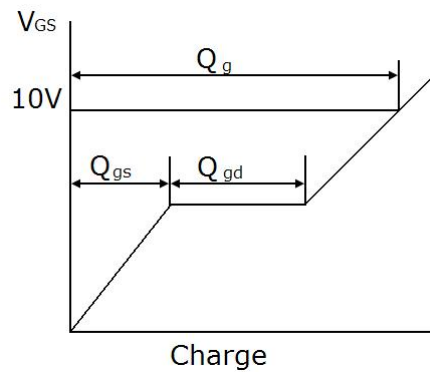
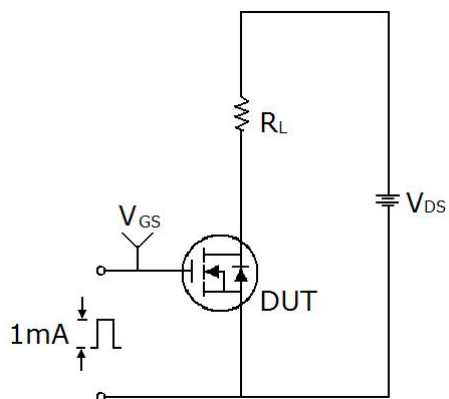


Figure10. Source-Drain Diode Forward Voltage

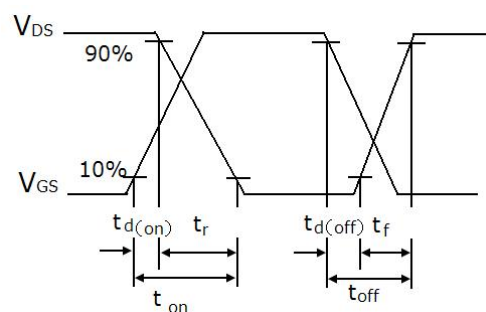


## Test circuit

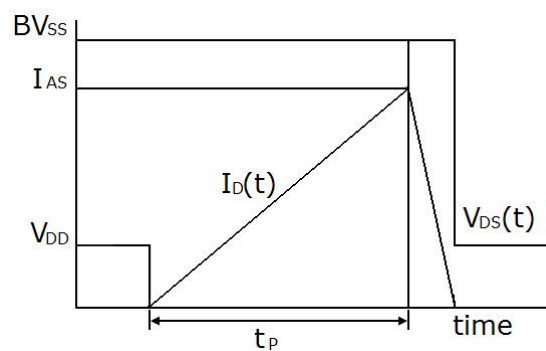
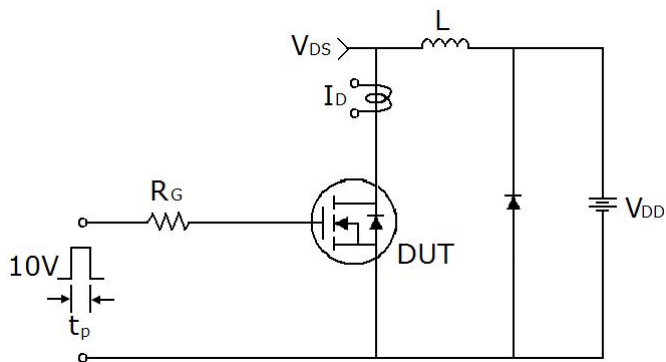
### 1) Gate charge test circuit & Waveform



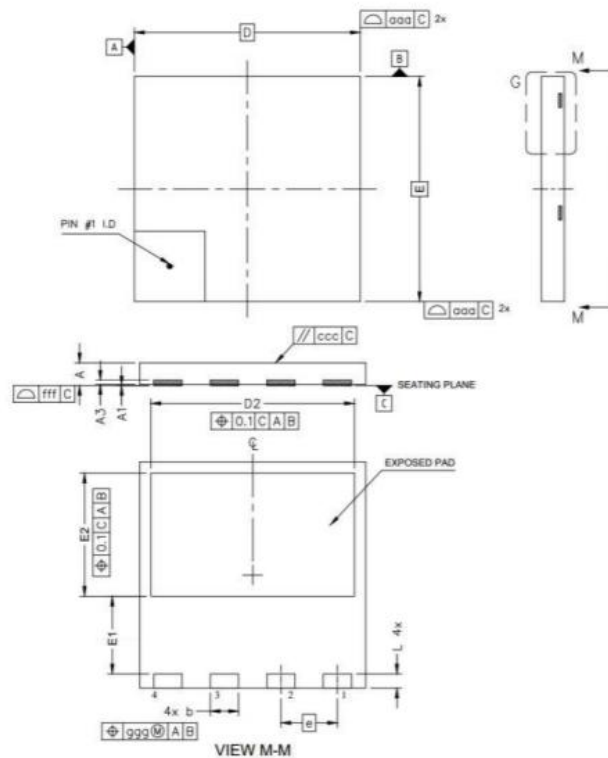
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## DFN8\*8 Package Information



DIM	MIN	NOM	MAX	NOTES
A	0.75	0.85	0.95	1.0 DIMENSIONING & TOLERANCEING CONFIRM TO ASME Y14.5M-1994. 2.0 ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES. 3.0 DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.90mm AND 1.10mm FROM TERMINAL TIP. 4.0 DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. 5.0 COPLANARITY APPLIES TO THE EXPOSED HEAT SLUG AS WELL AS THE TERMINAL. 6.0 RADIUS ON TERMINAL IS OPTIONAL.
A1	0.00		0.05	
A3	0.10	0.20	0.30	
b	0.90	1.00	1.10	
D	7.90	8.00	8.10	
E	7.90	8.00	8.10	
D2	7.10	7.20	7.30	
E1	2.65	2.75	2.85	
E2	4.25	4.35	4.45	
e		2.00 BSC		
L	0.40	0.50	0.60	
aaa		0.10		
ggg		0.05		
ccc		0.05		
fff		0.05		

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